

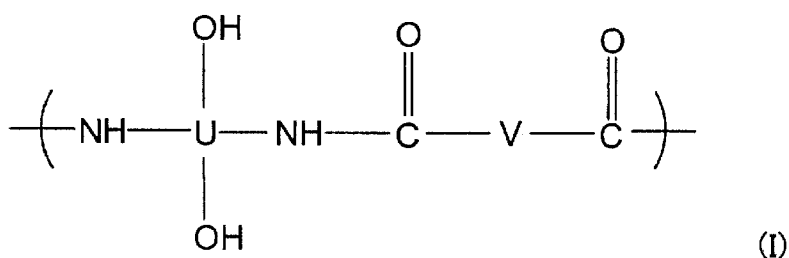
AMENDMENTS TO THE CLAIMS:

The following listing of claims replaces all prior listings, and all prior versions, of claims in the application.

LISTING OF CLAIMS:

1. (Cancelled).

2. (Previously presented) The positive photosensitive resin composition according to claim 18, wherein the component (a) is a polyamide having a repeating unit represented by the following general formula (I):



wherein U represents a tetravalent organic group, and V represents a divalent organic group.

3. (Cancelled).

4. (Previously presented) The positive photosensitive resin composition according to claim 18, wherein the component (c) has a decomposition starting temperature of 140 to 250°C.

5. – 9. (Cancelled).

10. (Previously presented) The positive photosensitive resin composition according to claim 18, wherein the content of the component (b) and the content of the component (c) are 5 to 100 parts by weight and 0.1 to 30 parts by weight, respectively, relative to 100 parts by weight of the component (a).

11. – 13. (Cancelled).

14. (Previously presented) The method according to claim 20, wherein the heating treatment is a treatment of irradiating the film with a pulse of microwave while changing the frequency thereof.

15. (Cancelled).

16. (Previously presented) An electronic part comprising an electronic device having a layer of pattern obtained by the method for forming a pattern according to claim 20,

wherein the device comprises the layer of pattern provided therein as any one of an interlayer insulating layer and a surface protecting film layer or both.

17. (Original) The electronic part according to claim 16 which is MRAM.

18. (Previously presented) A positive photosensitive resin composition comprising:

(a) alkaline aqueous solution-soluble polyamide having a polyoxazole precursor structure;

(b) an o-quinonediazide compound; and

(c) a latent acid generator which generates acid upon heating,

wherein said component (c) is selected from the group consisting of:

(c-1) imide sulfonate;

(c-2) a compound having a structure $R^1R^2C=N-O-SO_2-R$, wherein R is selected from a group consisting of an aryl group, an alkyl group and a perfluoroalkyl group; R^1 is a cyano group; and R^2 is selected from a group consisting of a methoxyphenyl group and a phenyl group;

(c-3) a compound having a structure $-HN-SO_2-R'$, wherein R' is selected from a group consisting of an alkyl group, an aryl group and a perfluoroalkyl group;

(c-4) a salt formed from a strong acid and a base selected from a group consisting of alkyl pyridine, pyridine, N-alkyl pyridine and halogenated N-alkyl pyridine, said salt being other than onium salts; and combinations thereof.

19. (Cancelled).

20. (Previously presented) A method for forming a pattern comprising the steps of:

applying a positive photosensitive resin composition onto a supporting substrate and drying the composition to obtain a photosensitive resin film;

exposing the photosensitive resin film to a ray of active light having a predetermined pattern;

developing the exposed photosensitive resin film using an alkaline aqueous solution; and

subjecting the developed photosensitive resin film to a heating treatment,

wherein said positive photosensitive resin composition comprises:

(a) alkaline aqueous solution-soluble polyamide having a polyoxazole precursor structure;

(b) an o-quinonediazide compound; and

(c) a latent acid generator which generates acid upon heating, said generator having a decomposition starting temperature of 140 to 250°C; and

wherein the heating treatment is conducted at a temperature equal to or lower than 280°C.

21. – 23. (Cancelled).